MTPL/SECT/29/2026-27 **Date: August 21, 2026**

To The Secretary, Listing Department, **BSE Limited,** Phiroze Jeejeebhoy Towers, Dalal Street, Fort, Mumbai-400001. **Scrip Code: 533080**	To The Manager, Listing Department, **National Stock Exchange of India Limited,** Exchange Plaza, 5th Floor, Plot No. C/1, G Block, Bandra Kurla Complex, Bandra (E), Mumbai-400051. **Symbol: MOLDTKPAC**

Sir/Madam,

Sub: Intimation of Board Meeting

Pursuant to Regulation 29 of the SEBI (Listing Obligations and Disclosure Requirements) Regulations, 2015 ("SEBI Listing Regulations"), as amended, we hereby inform you that, a meeting of the Board of Directors of the Company is scheduled to be held on Wednesday, August 26, 2026, inter-alia, to:

1. consider the proposal for issuance of fully paid Bonus Equity Shares to the existing equity shareholders of the Company.
2. discuss and consider increase in Authorized Share Capital of the Company, subject to approval of shareholders.
3. recommend final dividend, if any, on the equity shares of the Company for the Financial Year ended on March 31, 2026.
4. fix day, date, time and venue for convening the 29th Annual General Meeting of the Company and approval of the draft Notice thereof.
5. fix the Cut-off/Record date for the purpose of sending notice and payment of Final dividend for the Financial Year 2025-26, if declared, at the 29th AGM and e-voting for the said AGM.

This is for your information and records.

Thanking you,

For Mold-Tek Packaging Limited

LAKSHMANA RAO JANUMAHANTI
Digitally signed by LAKSHMANA RAO JANUMAHANTI
Date: 2026.08.21 10:22:55 +05'30'

Lakshmana Rao Janumahanti
Chairman and Managing Director
DIN: 00649702